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Date: 05/01/2000

Time: 14:18

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L13	993	heat adj (spreader slug)	USPAT; JPO	2000/05/01 14:01
2	BRS	L15	9	13 and (electrical adj2 shielding)	USPAT; JPO	2000/05/01 14:05
3	BRS	L16	546	13 and (solder ball)	USPAT; JPO	2000/05/01 14:10
4	BRS	L17	473	16 and (semiconductor chip)	USPAT; JPO	2000/05/01 14:08
5	BRS	L18	359	17 and substrate	USPAT; JPO	2000/05/01 14:09
6	BRS	L20	2	18 and snapped	USPAT; JPO	2000/05/01 14:09
7	BRS	L21	176	(13 AND (SOLDER adj BALL))	USPAT; JPO	2000/05/01 14:10
8	BRS	L22	103	(13 AND (SOLDER adj Bump))	USPAT; JPO	2000/05/01 14:11
9	BRS	L24	203	23 and (semiconductor chip)	USPAT; JPO	2000/05/01 14:12
10	BRS	L26	9	23 and flange	USPAT; JPO	2000/05/01 14:15
11	BRS	L27	214	23 not 15	USPAT; JPO	2000/05/01 14:17
12	BRS	L28	218	21 22	USPAT; JPO	2000/05/01 14:17

	Comments	Error Definition	Errors
1			0
2			0
3			0
4			0
5			0
6			0
7			0
8			0
9			0
10			0
11			0
12			0